EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	205858	(substrate wafer).clm.	US-PGPUB	OR	ON	2008/01/18 10:19
L2	2544	(conductive near5 trace). clm.	US-PGPUB	OR	ON	2008/01/18 10:20
L3	68064	(die chip IC).clm.	US-PGPUB	OR	ON	2008/01/18 10:20
L4	27230	(ball baump).clm.	US-PGPUB	OR	ON	2008/01/18 10:21
L6	215	((ball bump) same (conductive near10 trace)). clm.	US-PGPUB	OR	ON	2008/01/18 10:23
L7	2621	(BGA (grid near5 array)). clm.	US-PGPUB	OR	ON	2008/01/18 10:23
L8	6518	((die chip IC) near10 (pad adaptor)).clm.	US-PGPUB	OR	ON	2008/01/18 10:24
L9	21	1 and 2 and 3 and 4 and 6 and 7 and 8	US-PGPUB	OR	ON	2008/01/18 10:25

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21736	(BGA (ball near5 grid near5 array))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/18 10:08
L2	1310	L1 and (conductive near15 trace near15 ball)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/18 10:08
L3	1037	L2 and ((die chip IC) near5 (pad adapter))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/18 10:08
L4	13358	(BGA (ball same grid same array))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/18 10:09
L6	154	4 and (conductive same trace same ball)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/18 10:10
L7	72	6 and ((die chip IC) same (pad adapter))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/18 10:10